

ABSTRACT

A semiconductor device testing apparatus is provided which allows for eliminating the need to replace IC sockets even if the type of IC package is changed. A device receiving carrier 100 accommodating the IC to be tested has its bottom open. A fine conductive wire-embedded member 110 is mounted to the open bottom of the device receiving carrier. The wire-embedded member comprises a resilient rubber plate 111 and a number of fine conductive wires 112 embedded in the rubber plate, the fine conductive wires being electrically insulated from each other and extending through the thickness of the rubber plate with the opposite ends exposed at the opposed surfaces of the rubber plate. The IC to be tested is rested on the wire-embedded member. A board 70 is mounted to the test head, said board having gold pads 72 formed in a manner electrically insulated from each other in the surface thereof at at least the positions opposing the terminals of the IC to be tested placed on the top surface of the wire-embedded member. During the testing of the IC in the test section, the bottom surface of the wire-embedded member is put into contact with the board to establish electrical connection between the terminals of the IC and the corresponding gold pads of the board through the fine conductive wires of the wire-embedded member.